5788667-1 ✕ OBSOLETE

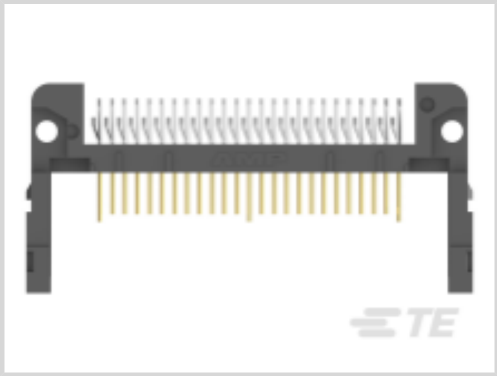
TE Internal #: 5788667-1

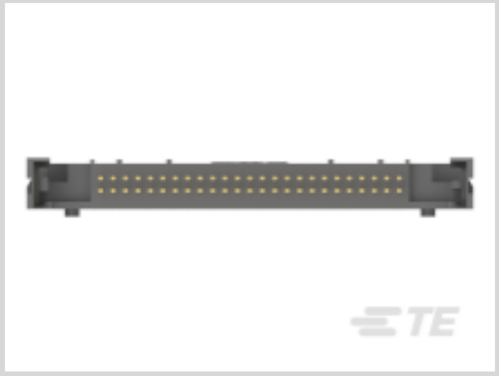
TE Internal Description: 50 RA SMT HDR COMPACT FLASH

View on TE.com >

Connectors > PCB Connectors > Memory Card Connectors > CompactFlash Connectors







Connector System: **Cable-to-Board**

Number of Positions: **50**

Centerline (Pitch): **1.27 mm [.05 in]**

Number of Rows: **2**

PCB Mounting Style: **Surface Mount, Surface Mount Staggered Leads**

Features

Product Type Features

Format	CompactFlash
CompactFlash Product Type	Header Only
PCB Offset	0 mm[0 in]
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Removable Memory Products
Shielded	No
Profile	Low

Configuration Features

Lead Configuration	Staggered
Number of Positions	50
Number of Rows	2
PCB Mount Orientation	Right Angle

Body Features

Hold-Down	Without

Color	Black

Contact Features

Vacuum Tape	Without
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Beryllium Copper
Contact Current Rating (Max)	.5 A
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Thickness	30 µin

Mechanical Attachment

PCB Mounting Style	Surface Mount, Surface Mount Staggered Leads
Connector Mounting Type	Board Mount

Housing Features

Centerline (Pitch)	1.27 mm[.05 in]
Housing Material	LCP (Liquid Crystal Polymer)

Dimensions

Profile Height from PCB	3.51 mm

Operation/Application

Circuit Application	Signal

Industry Standards

UL Flammability Rating	UL 94V-0

Packaging Features

Packaging Method	Reel

Other

Comment	Two size M2 screws (customer supplied) are required for fastening the connector to the PC board.

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant

China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUL 2021 (219) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5788667-1_O.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_5788667-1_O.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5788667-1_O.3d_stp.zip

English

By downloading the CAD file I accept and agree to the Terms and Conditions of use.

Product Environmental Compliance

TE Material Declaration

English